www.telace.co.kr Preliminary

G1000M GNSS Receiver chip

(GPS L1/L2,Glonass,Beidou,Galileo, SBAS - WAAS,MSAS,SDCM,Beidou SBAS)



High Performance GNSS Navigation

- · Adaptive operation for high sensitivity and dynamics
- · Adaptive/modifiable tracking loop and filter techniques against multipath environments
- · Patented fast acquisition architecture
- · 40 tracking channel support at the same time

Multiple GNSS Support

- · Support GPS L1/L2, GLONASS, Beidou, Galileo, SBAS L1 frequency (WAAS, MSAS, SDCM, BEIDOU SBAS)
- · Support GPS L2C frequency

Multiple Environments Support

· Stationary, land vehicle, high dynamic airborne, LEO, meteorological and military area

Multiple Protocols Support

· Support for NMEA, TGb(Telace GPS Binary Protocol), customer dependent protocol

GNSS-INS integration ready

 Support for navigation with integrated GNSS and INS

High Accuracy

 Support SBAS correction, RTCM, dual frequency ionospheric correction, carrier smoothing

System on Chip

· Low power single chip including RF, baseband, CPU, and memory

AGPS Support

· Fast position fix with aiding information

Flexible Interface

 Support EMI, I2C, UART, SPI, GPIO, HSDLC interface

Automotive Interface

 Support automotive direction, speed interface



PERFORMANCE

Channels 40

Signal Tracking

GPS
GLONASS
Beidou
Galileo
SBAS
L1 C/A,L2C
B1
E1
L1 C/A

Position Accuracy⁽¹⁾

Single Position 2m
 Dual Position(L1/L2) TBD
 SBAS 1m
 DGNSS 1m
 Velocity Accuracy⁽¹⁾ 0.5 m/s

Acceleration⁽²⁾
Sensitivity

· Acquisition -145 dBm · Tracking -162 dBm

10g

PPS Accuracy 50 ns

TTFF

Hot Start Warm Start Cold Start 2s 12s 30s

Update Rate⁽³⁾ 10Hz

Features

Differential GPS positioning with SBAS
Differential GPS positioning with RTCM
Assist GPS for Fast First Fix
Fast Error Detection and Exclusion
INS integrated navigation ready
Carrier smoothing
Dual-frequency lonospheric Correction

INTERFACES

Communication Port UART 4
SPI 4
HSDLC 1
GPIO 8
EMI 1

PPS 1 Hz Configurable Rate

I2C

NMEA 0183

Protocols

TGb TelAce GPS Binary Protocol RTCM For DGNSS OEM CustomerDependent

1

ELECTRICAL AND PHYSICAL

Dimensions 14mm x 14mm x 1.4mm

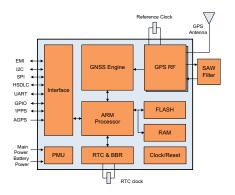
Weight

Supply voltage(BB) $1.65V \sim 3.6V$ Supply voltage(RF) $2.7V \sim 3.3V$ Power consumptionT.B.D.Temperature $-40 \,^{\circ}\text{C} \sim 85 \,^{\circ}\text{C}$

Memory On Chip FLASH

RF On Chip and External RF

BLOCK DIAGRAM



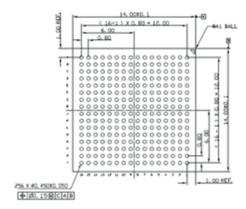
PACKAGE

G1000M Type: FBGA

Ball : 256 ball

Size : 14mm X 14mm X 1.4mm

Pitch: 0.8mm



Contact US

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- (2) It depends on platform mode configuration
- (3) There may be a limit to the number of channels

